



2814 #40  
J. H. H.  
3-27-02

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

BOX AF

In re the Application of:

Norio FUKASAWA et al

Serial Number: 09/029,608

Group Art Unit: 2814

Filed: May 15, 1998

Examiner: Graybill, D.

For: METHOD AND MOLD FOR MANUFACTURING SEMICONDUCTOR DEVICE,  
SEMICONDUCTOR DEVICE AND METHOD FOR MOUNTING THE DEVICE

AMENDMENT AFTER FINAL REJECTION

BOX AF

Commissioner for Patents  
Washington, D.C. 20231

January 18, 2002

Sir:

In response to the Office Action dated October 19, 2001, please amend the above-identified application as follows:

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TECHNOLOGY CENTER 2800

IN THE CLAIMS:

Please cancel claims 18, 19, 36, 41-43, 82, 91, 95-102, 113 and 114 without prejudice or disclaimer.

Please amend claims 109-111, 115-117, 119, 122, 123 and 129 as follows:

109. (Amended) A semiconductor device comprising:

a semiconductor element having a surface on which protruding electrodes are formed;

a resin layer formed on the surface of the semiconductor element so as to seal the protruding electrodes except end portions thereof; and

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